

Description

The SX30N15D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 150V$ $I_D = 30A$

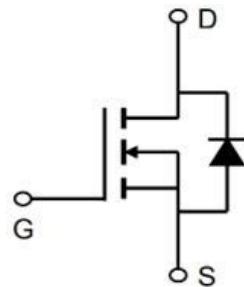
$R_{DS(ON)} < 52m\Omega @ V_{GS}=10V$

Application

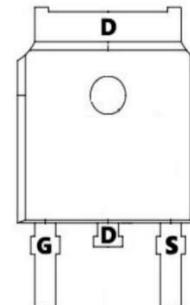
Battery protection

Load switch

Uninterruptible power supply



TO-252-3L



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current ¹	30	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current ¹	16	A
$I_D @ T_A=25^\circ C$	Continuous Drain Current ¹	4.5	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current ¹	3.8	A
IDM	Pulsed Drain Current ²	60	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation ³	72.6	W
$P_D @ T_A=25^\circ C$	Total Power Dissipation ³	2.7	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C
R_{eJA}	Thermal Resistance Junction-ambient ¹	55	°C/W
R_{eJC}	Thermal Resistance Junction-Case ¹	2.0	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	150	165	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=20\text{A}$	---	43	52	$\text{m}\Omega$
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=10\text{A}$	---	45	70	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.8	2.5	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=120\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=120\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=10\text{A}$	---	25	---	S
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$	---	23	---	nC
Q_{gs}	Gate-Source Charge		---	5.8	---	
Q_{gd}	Gate-Drain Charge		---	4.2	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=3.3\Omega$ $\text{I}_D=10\text{A}$	---	16.2	---	ns
T_r	Rise Time		---	18.6	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	28.5	---	
T_f	Fall Time		---	6.5	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=75\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1190	---	pF
C_{oss}	Output Capacitance		---	73	---	
C_{rss}	Reverse Transfer Capacitance		---	4	---	
I_s	Continuous Source Current ^{1,4}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	20	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=10\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	45	---	nS
Q_{rr}	Reverse Recovery Charge		---	138	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

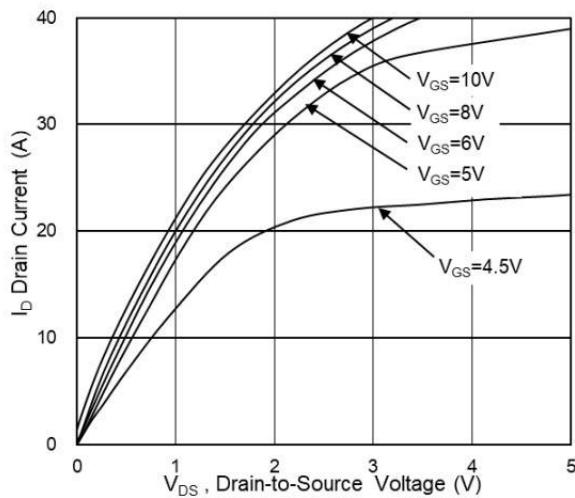


Fig.1 Typical Output Characteristics

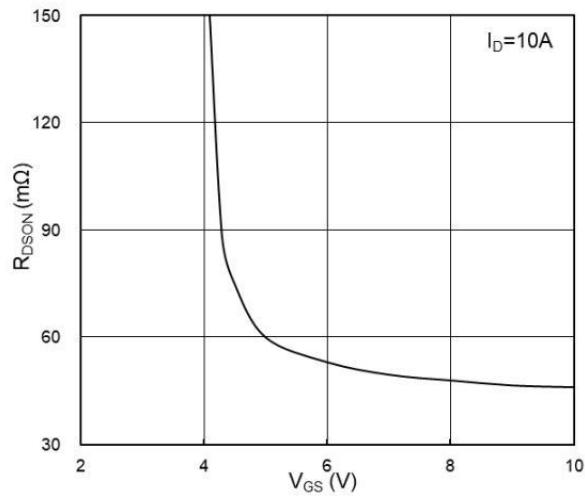


Fig.2 On-Resistance vs G-S Voltage

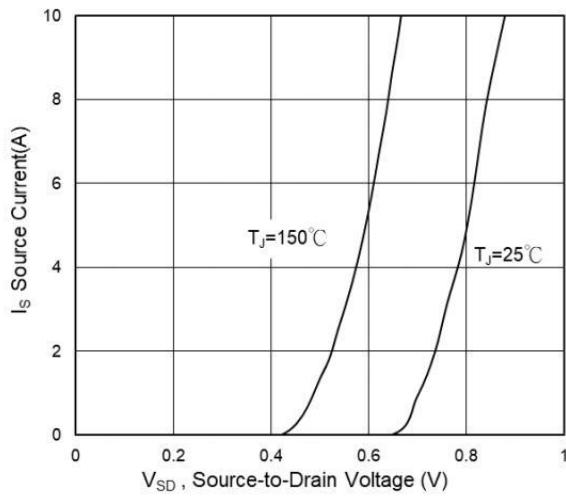


Fig.3 Source Drain Forward Characteristics

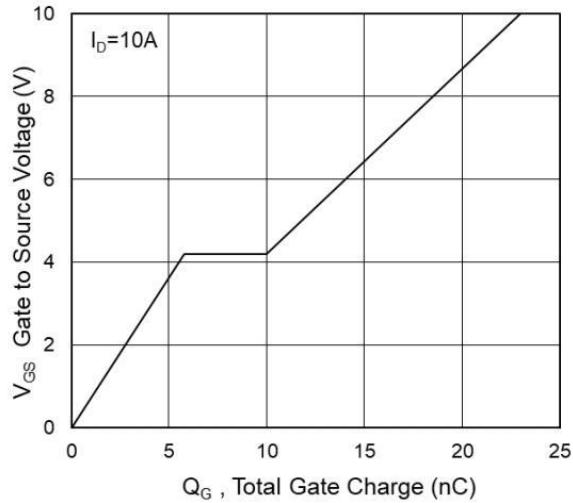


Fig.4 Gate-Charge Characteristics

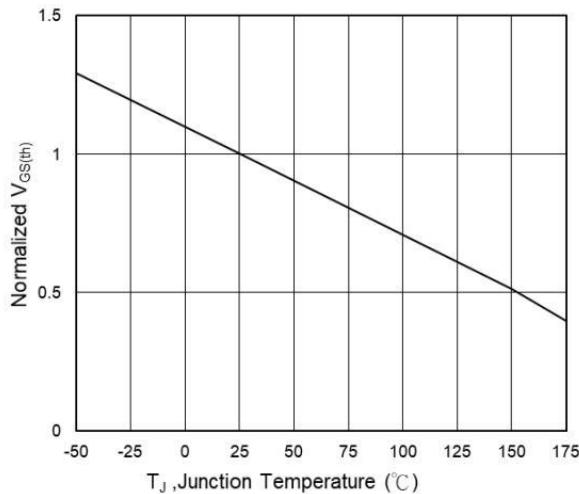


Fig.5 Normalized $V_{GS(th)}$ vs T_J

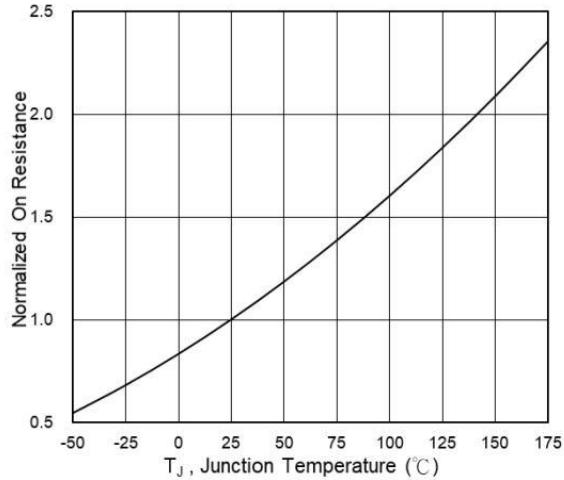


Fig.6 Normalized $R_{DS(on)}$ vs T_J

Typical Characteristics

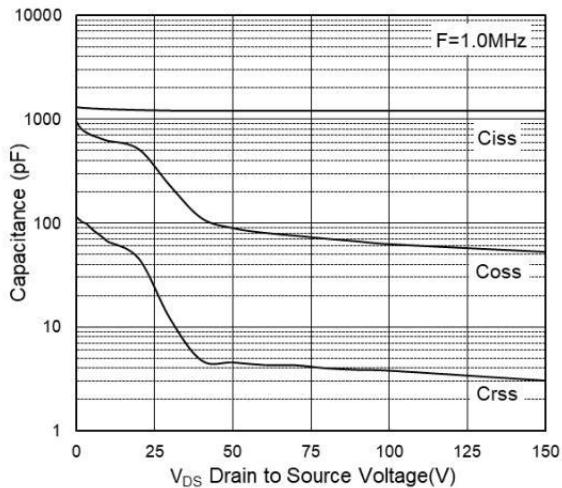


Fig.7 Capacitance

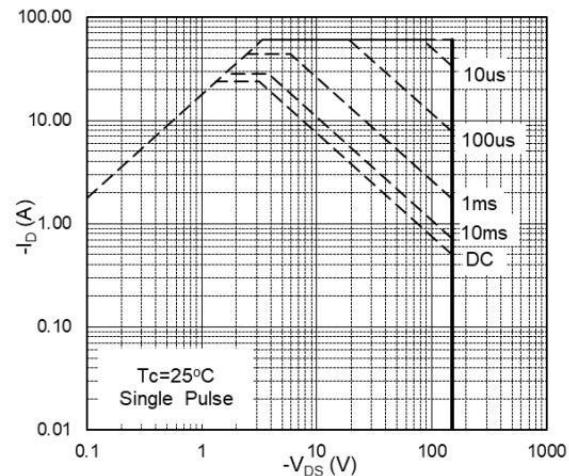


Fig.8 Safe Operating Area

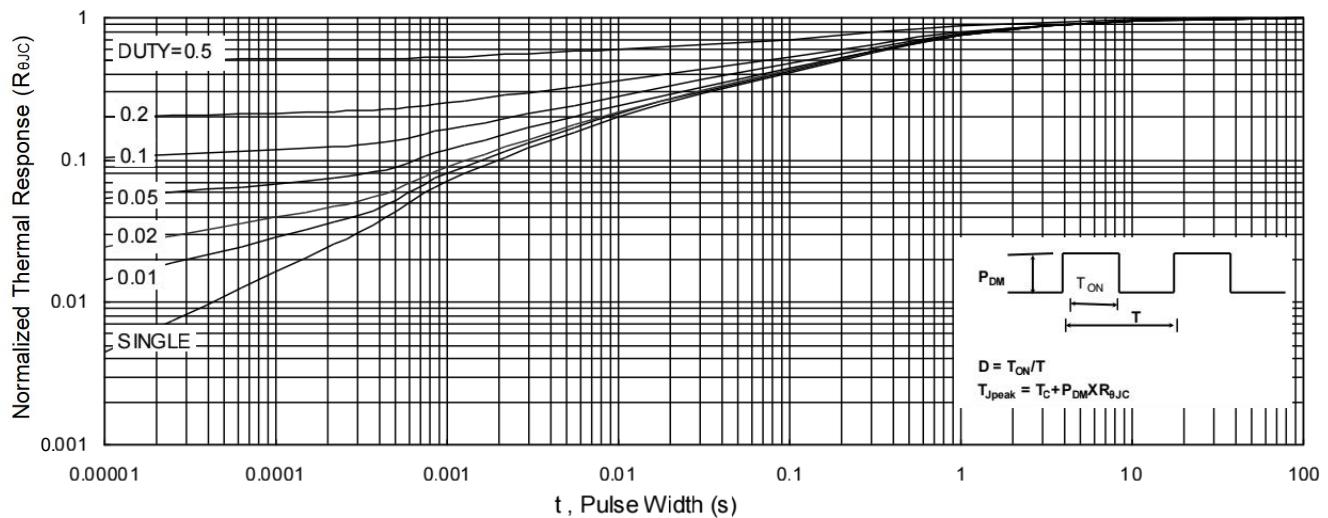


Fig.9 Normalized Maximum Transient Thermal Impedance

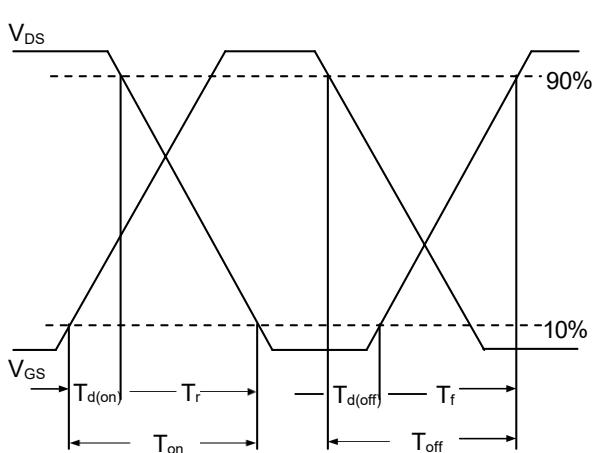


Fig.10 Switching Time Waveform

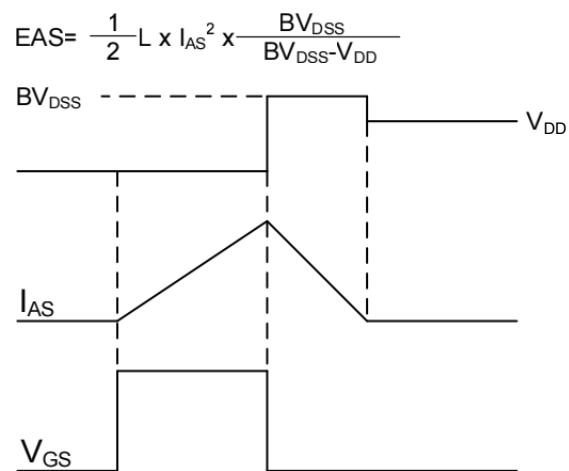
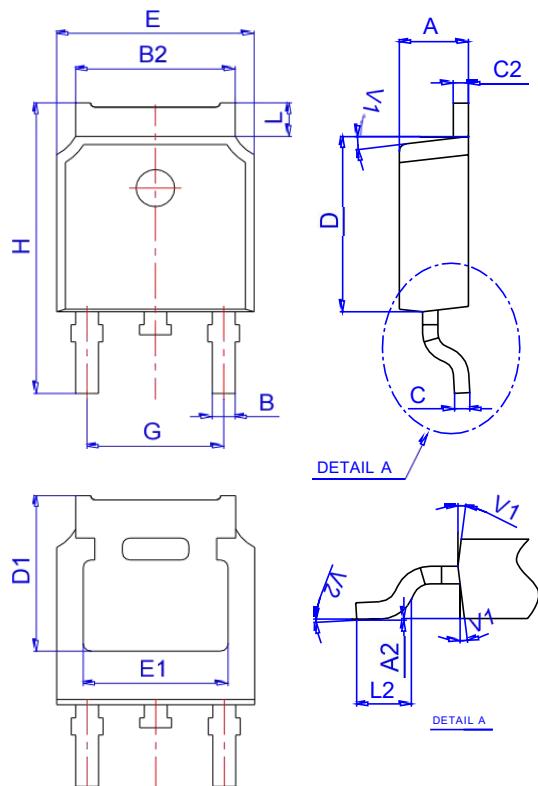


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data : TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-252-3L		2500